

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Harry A. ATWATER, Jr. et al.

Title:

WAFER BONDED VIRTUAL SUBSTRATE AND METHOD FOR FORMING THE SAME

Appl. No.:

10/761,918

Filing Date:

1/20/2004

Examiner:

Duy-Vu DEO

Art Unit:

1765

Confirmation

4108

Number:

SUPPLEMENTAL AMENDMENT AND REPLY UNDER 37 CFR 1.111

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

This communication is responsive to the Non-Final Office Action dated May 11, 2006 and supplemental to the Amendment filed on August 11, 2006, concerning the above-referenced patent application.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this document.

Remarks/Arguments begin on page 7 of this document.

Please amend the application as follows: